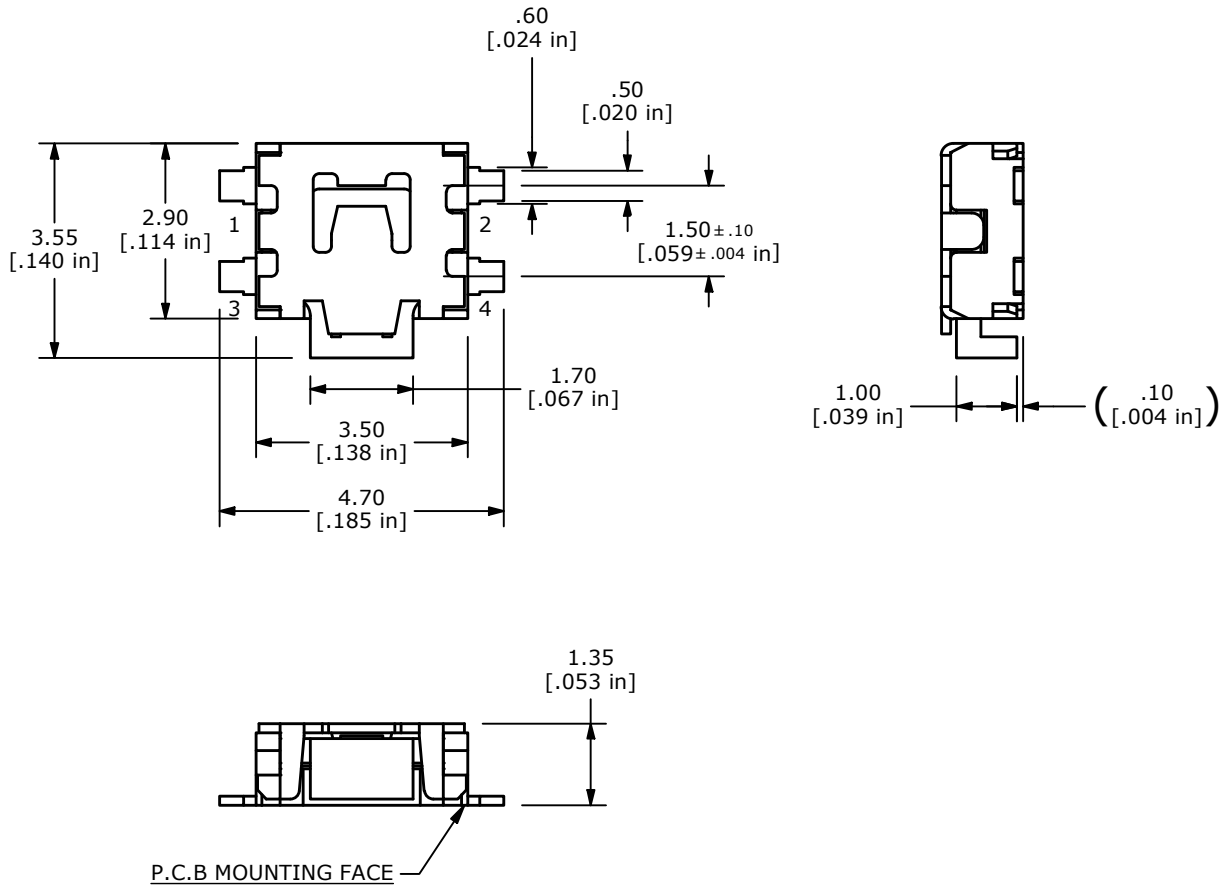
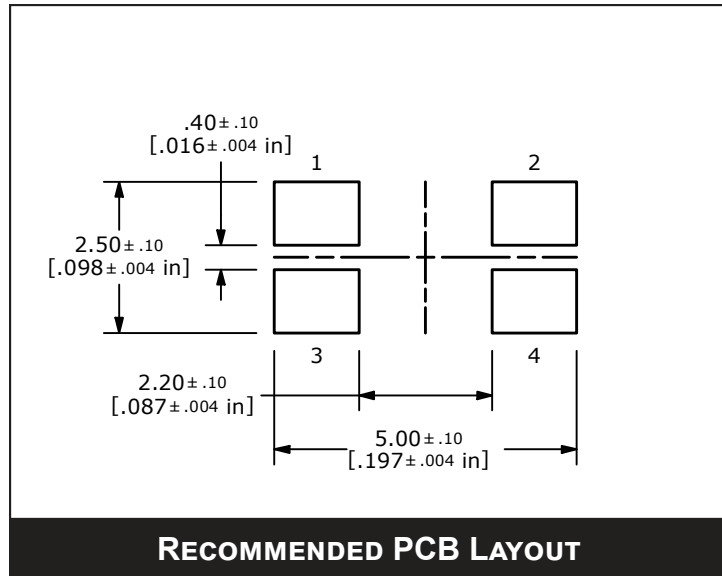
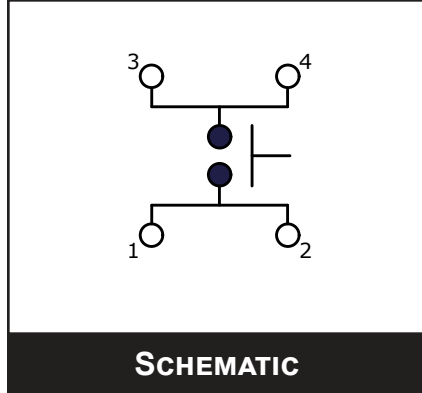




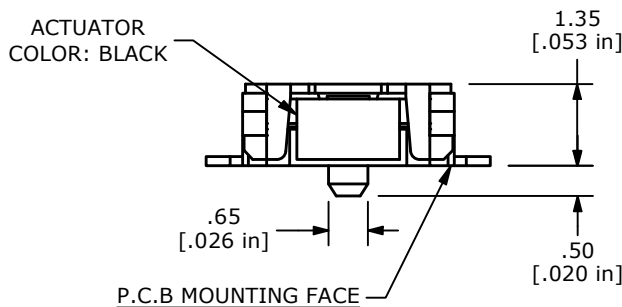
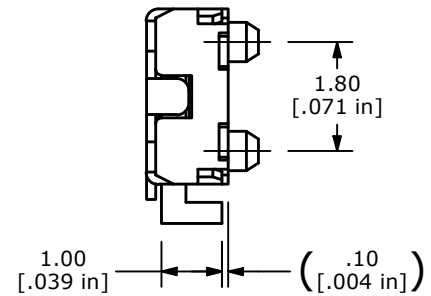
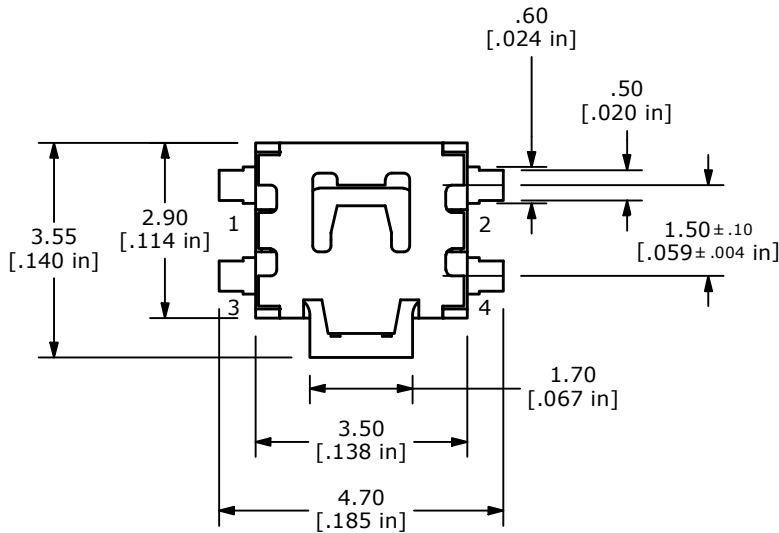
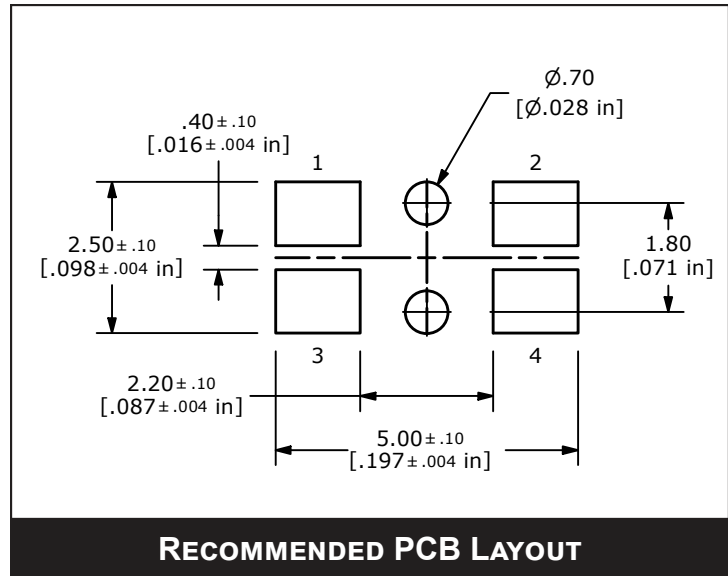
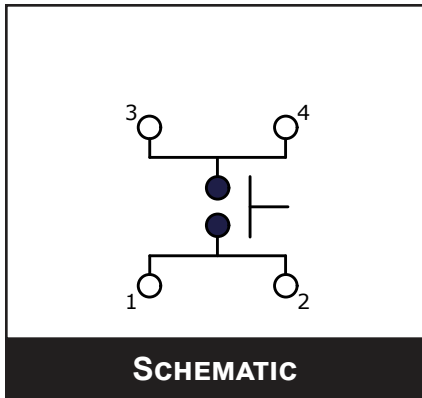
# TL1016 SERIES TACT SWITCH

## BODY DIMENSIONS WITHOUT BOSSES AND GROUND TERMINAL



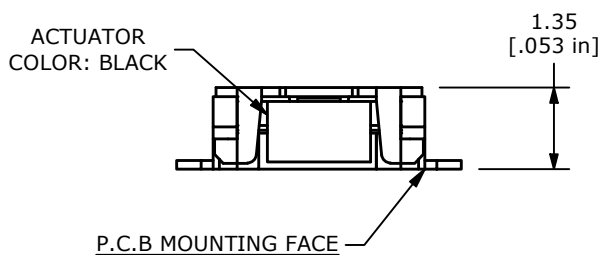
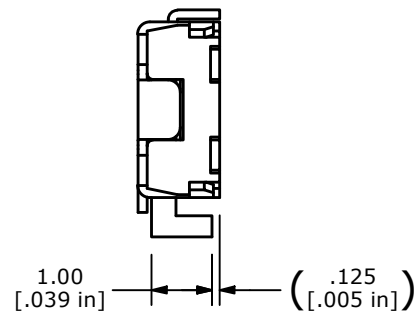
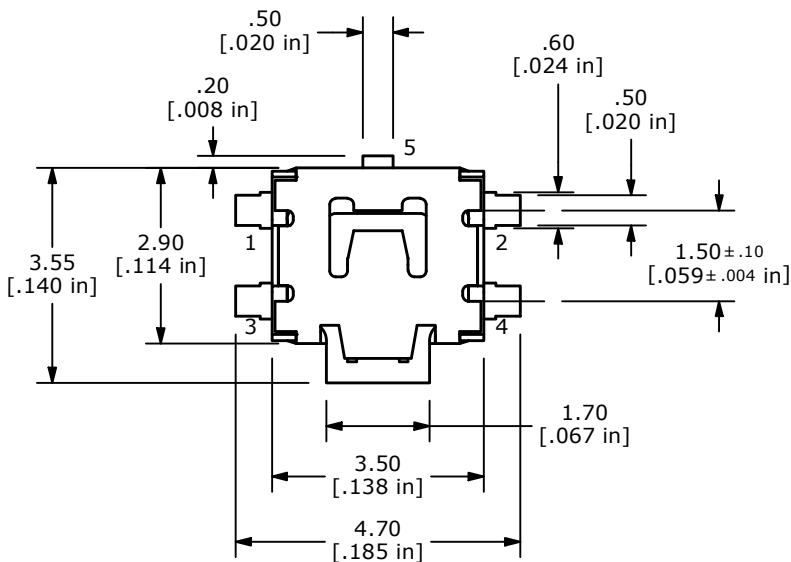
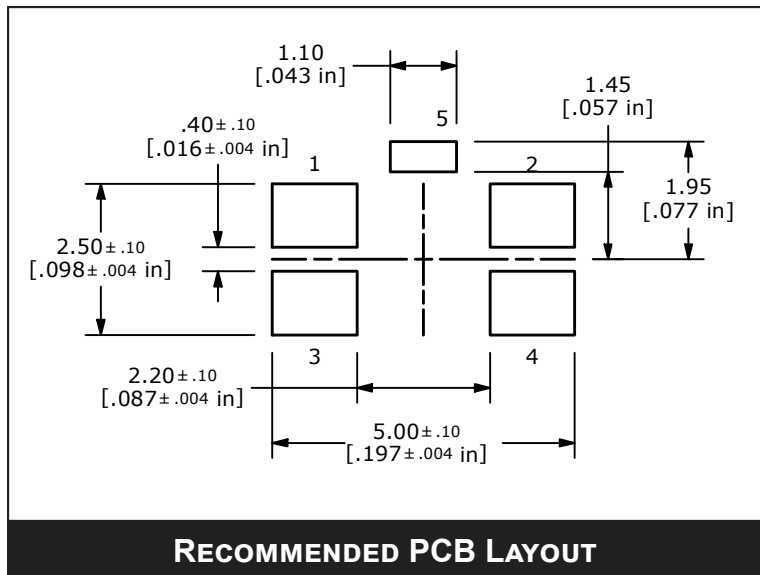
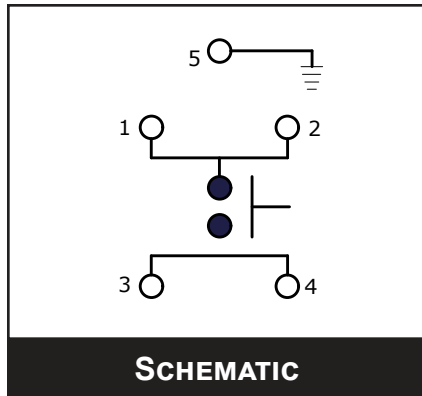
# TL1016 SERIES TACT SWITCH

## BODY DIMENSIONS WITH BOSSES AND WITHOUT GROUND TERMINAL



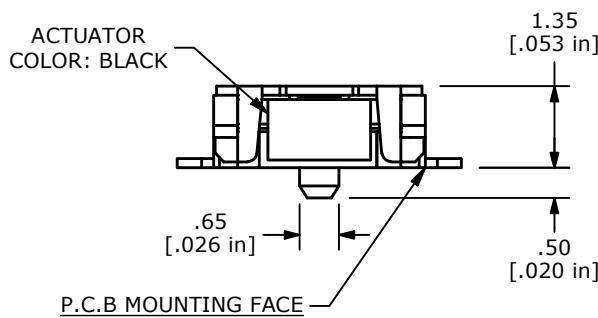
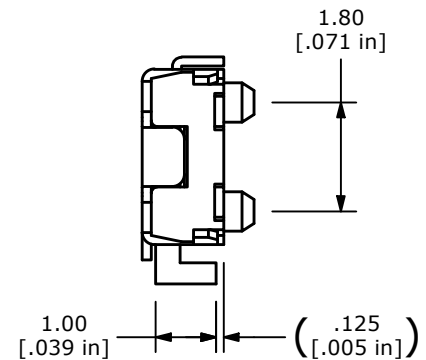
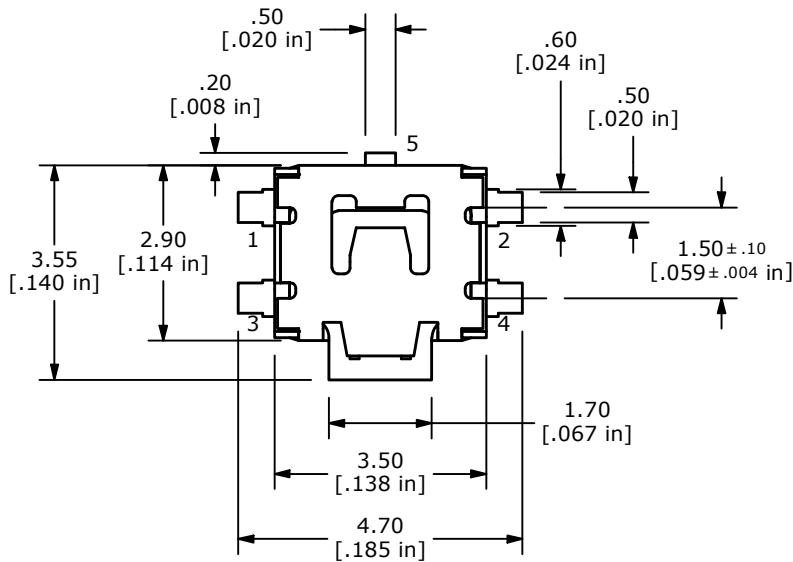
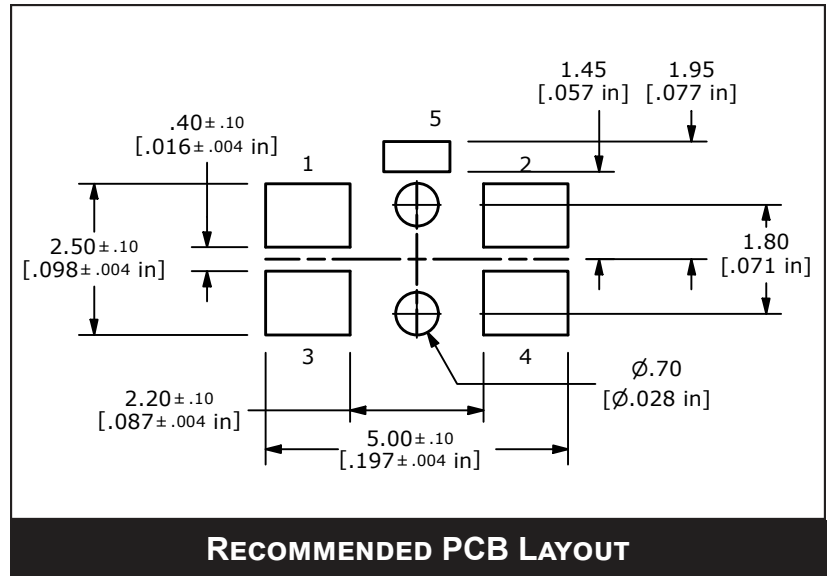
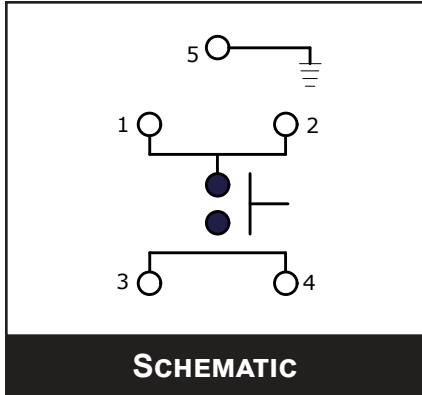
# TL1016 SERIES TACT SWITCH

## BODY DIMENSIONS WITH GROUND TERMINAL AND WITHOUT BOSSES



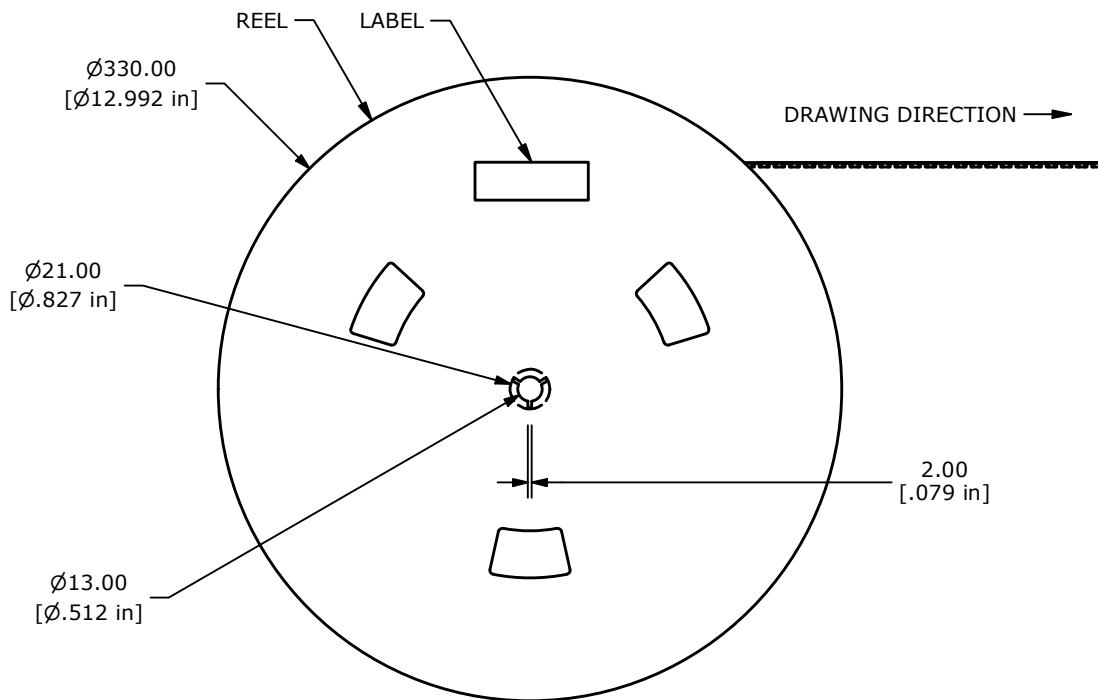
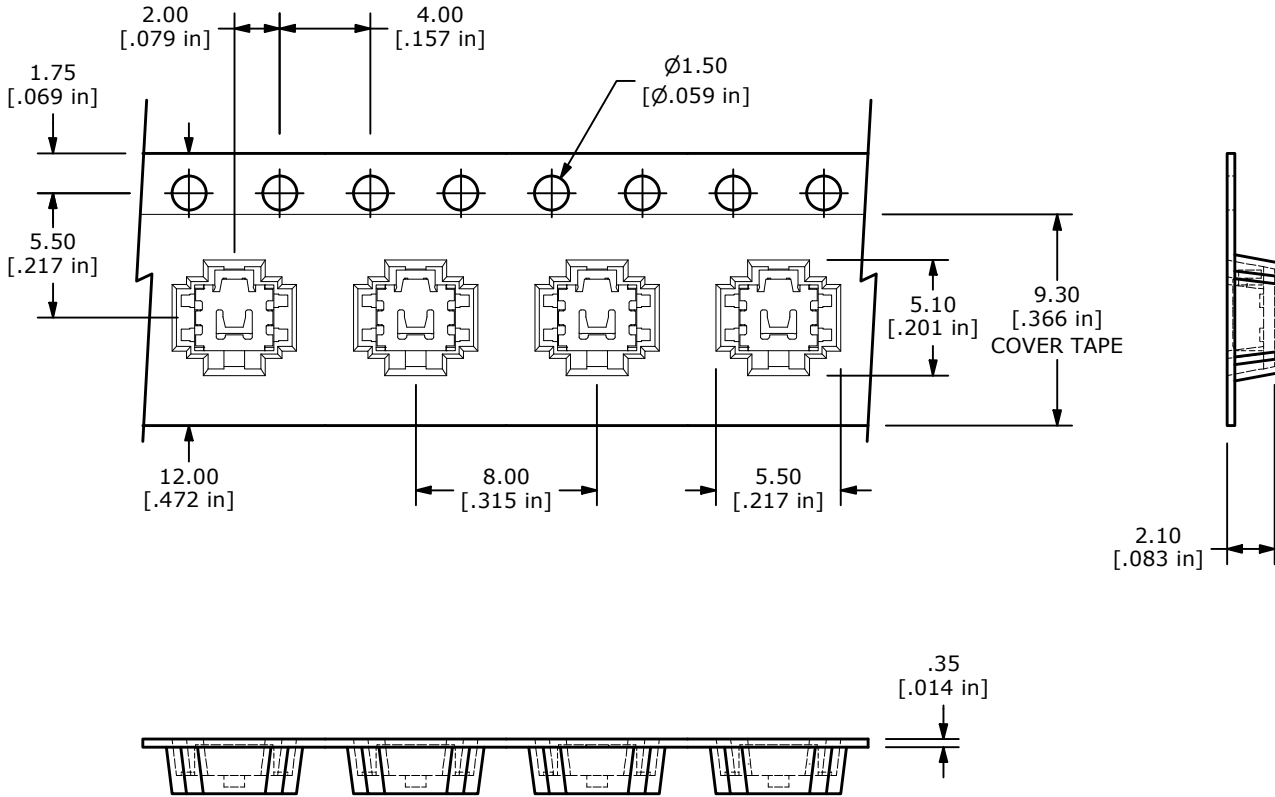
# TL1016 SERIES TACT SWITCH

## BODY DIMENSIONS WITH BOSSES AND GROUND TERMINAL



# TL1016 SERIES TACT SWITCH

## BODY DIMENSIONS TAPE AND REEL



# TL1016 SERIES TACT SWITCH

## RECOMMENDED SOLDER PROCESS

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

### “TYPICAL” SMT REFLOW (Pb and Pb-Free)

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate ( $T_{s_{max}}$ to $T_p$ )	3 °C/second max.	3 °C/second max.
<b>Preheat</b>		
-Temperature Min ( $T_{s_{min}}$ )	100 °C	150 °C
-Temperature Max ( $T_{s_{max}}$ )	150 °C	200 °C
-Time ( $t_{s_{min}}$ to $t_{s_{max}}$ )	60-120 seconds	60-180 seconds
Time Maintained above:		
-Temperature ( $T_L$ )	183 °C	217 °C
-Time ( $t_L$ )	60-150 seconds	60-150 seconds
Time within 5 °C of actual Peak Temperature ( $t_p$ )	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

**Note 1:** All temperatures refer to topside of the package, measured on the package surface.

